

## QUALCOMM

5775 Morehouse Drive San Diego, CA 92121-1714 (858) 587-1121 www.qualcomm.com

31 July 2015

Ms. Susanna Kooistra Mr. Patrick Merias ETSI, MCC 650, route des Lucioles Sophia-Antipolis France

Subject: Nomination of candidate for the 3GPP TSG RAN1 Vice Chairman

Dear Ms. Kooistra and Mr. Merias:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Dr. Wanshi Chen as a candidate for the position of 3GPP TSG RAN1 Vice Chairman at the upcoming election in RAN1#82.

Dr. Chen will be trained to comply with all applicable antitrust/competition laws and regulations while acting in his capacity as TSG RAN WG1 Vice Chairman.

In proposing Dr. Chen for the position of 3GPP TSG RAN1 Vice-Chairman, Qualcomm will fully support Dr. Chen in the vice-chairmanship role. Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

Dr. Chen is currently a 3GPP TSG RAN1 Vice Chairman; he was appointed in August 2013. A brief curriculum vitae of Wanshi Dr. Chen is attached.

Best Regards,

Edward D. Justeman

Edward G. Tiedemann, Jr. Senior Vice-President, Engineering QUALCOMM Technologies, Inc.

## Wanshi Chen

Wanshi Chen has over 15 years experiences in telecommunications in leading telecom companies including operators, infrastructure vendors, and user equipment vendors. From 1996 to 1997, he worked at China Mobile focusing on wireless network installation, maintenance, field test and debugging, performance characterization and optimization. From 2000 to 2006, he worked for Ericsson Wireless Communications, San Diego, responsible for 3GPP2 related system design, integration and performance optimization for commercial products, and 3GPP2 standardization.

In May 2006, Wanshi Chen joined Qualcomm, San Diego, where, as one of the key team members, has been contributing to the design, development and specification of LTE standardization through active participation in 3GPP RAN1.

The highest degree that Wanshi Chen has received is a Ph.D. degree in electrical engineering from the University of Southern California, Los Angeles, CA, USA.